### 501927186 05/21/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Chun-Ting KUO	03/05/2012
Kei-Wei CHEN	03/05/2012
Ying-Lang WANG	03/05/2012
Kuo-Hsiu WEI	03/05/2012

#### RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13408327

### **CORRESPONDENCE DATA**

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER: T5057-716

NAME OF SUBMITTER: Randy A. Noranbrock

**Total Attachments: 1** 

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PATENT REEL: 028239 FRAME: 0724 OP \$40.00 13408327

Docket No. T5057-716 TSMC2012-0011

# ASSIGNMENT

In consideration of the premises and ot	ther good and valuable consider	ration in hand paid, the receipt	and sufficiency of
which is hereby acknowledged, the undersigned,			

1) Chun-Ting KUO

4) Kuo-Hsiu WEI

- 2) Kei-Wei CHEN
- 3) Ying-Lang WANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

# TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

### 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

#### WAFER EDGE TRIM BLADE WITH SLOTS

(a)	for which an application for United States Letters Patent was filed on 2012-02-29	,	and	identified	by	United
	States Patent Application No. 13/408, 327; or					

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_\_

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chun - Ting Kus	2012. 3.5
Name: Chun-Ting KUO d	Date:
2) Culu Chon Name Kei-Wei CHEN	2012,3,5
Name Kei-Wei CHEN	Date:
3) _ Ving- Lang Wang	2012, 3,5
Name: Ying-Lang WANG	Date:
4) Kao-Hain Wei	2012. 7. 5
Name: Kuo-Hsiu WEI	Date:

PATENT REEL: 028239 FRAME: 0725

RECORDED: 05/21/2012